

#### **DESCRIPTION**

The SPN80T10 is the N-Channel logic enhancement mode power field effect transistor which is produced using super high cell density DMOS trench technology. The SPN80T10 has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low RDS(ON) and fast switching speed.

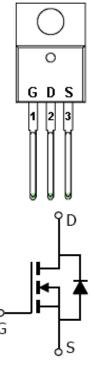
# APPLICATIONS

- Powered System
- DC/DC Converter
- Load Switch

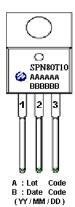
#### **FEATURES**

- 100V/85A, RDS(ON)=7.1m $\Omega$ @VGS=10V
- ♦ High density cell design for extremely low RDS (ON)
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ TO-220 package design

# PIN CONFIGURATION TO-220



#### **PART MARKING**



#### PIN DESCRIPTION

Pin	Symbol	Description
1	G	Gate
2	D	Drain
3	S	Source

#### **ORDERING INFORMATION**

Part Number	Package	Part Marking
SPN80T10T220TGB	TO-220-3L	SPN80T10

<sup>※</sup> SPN80T10T220TGB: Tube; Pb − Free; Halogen - Free

#### **ABSOULTE MAXIMUM RATINGS**

(Ta=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit	
Drain-Source Voltage		Vdss	100	V
Gate –Source Voltage		VGSS	±25	V
Continuous Drain Current(Tr-150°C)	TA=25°C	ID	85	Δ.
Continuous Drain Current(T <sub>J</sub> =150°C)	Ta=70°C		60	A
Pulsed Drain Current		Ідм	300	A
Power Dissipation @ TA=25°C		PD	166	W
Operating Junction Temperature		Тл	-55/150	$^{\circ}\!\mathbb{C}$
Storage Temperature Range		Tstg	-55/150	$^{\circ}\!\mathbb{C}$
Thermal Resistance-Junction to Ambient		RθJA	62	°C/W

## **ELECTRICAL CHARACTERISTICS**

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static	•			•	•		
Drain-Source Breakdown Voltage	V(BR)DSS	V <sub>GS</sub> =0V,I <sub>D</sub> =250uA	100			V	
Gate Threshold Voltage	VGS(th)	V <sub>GS(th)</sub> V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250uA			4.0	\ \ \ \	
Gate Leakage Current	Igss	V <sub>DS</sub> =0V,V <sub>GS</sub> =±25V			±100	nA	
Zero Gate Voltage Drain Current	Idss	V <sub>DS</sub> =80V,V <sub>GS</sub> =0V V <sub>DS</sub> =80V,V <sub>GS</sub> =0V T <sub>J</sub> =125°C			25 100	uA	
Drain-Source On-Resistance	RDS(on)	V <sub>GS</sub> = 10V,I <sub>D</sub> =40A			7.1	mΩ	
Forward Transconductance	gfs	VDS=10V,ID=40A		75		S	
Diode Forward Voltage	Vsd	Is=30A,VGS =0V			1.3	V	
Dynamic							
Total Gate Charge	Qg			115	180	nC	
Gate-Source Charge	Qgs	V <sub>DS</sub> =80V,V <sub>GS</sub> =10V I <sub>D</sub> = 40A		20			
Gate-Drain Charge	Qgd	-ID- 40A		48			
Input Capacitance	Ciss			6000	9600	pF	
Output Capacitance	Coss	V <sub>DS</sub> =25,V <sub>GS</sub> =0V f=1MHz		550			
Reverse Transfer Capacitance	Crss			300		<b>1</b>	
T. 0 T'	td(on)			21		nS	
Turn-On Time	tr	$V_{DD}=50V,R_{L}=1\Omega$		58			
T. OMT.	td(off)	ID=30A, VGEN=10V RG=1.66 $\Omega$		41			
Turn-Off Time	tf			15			



## TYPICAL CHARACTERISTICS

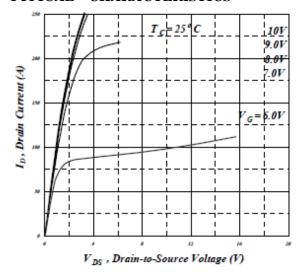


Fig 1. Typical Output Characteristics

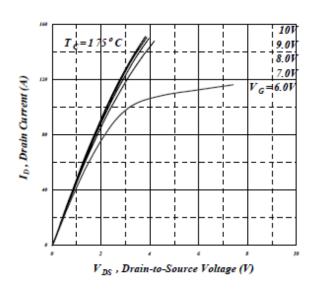


Fig 2. Typical Output Characteristics

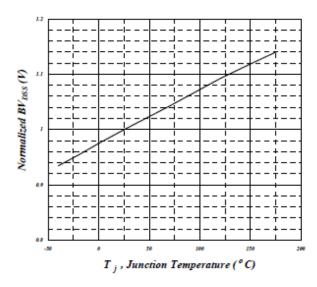


Fig 3. Normalized BV<sub>DSS</sub> v.s. Junction Temperature

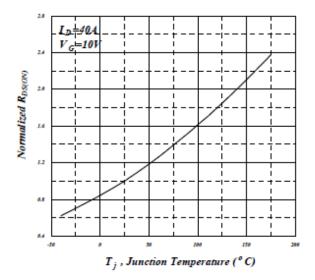


Fig 4. Normalized On-Resistance v.s. Junction Temperature

#### TYPICAL CHARACTERISTICS

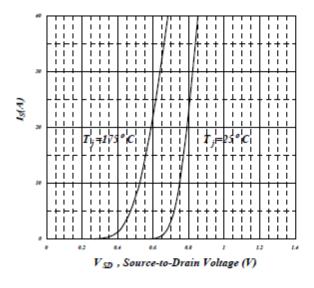


Fig 5. Forward Characteristic of Reverse Diode

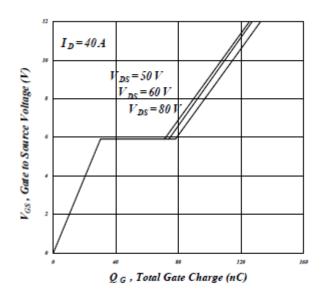


Fig 7. Gate Charge Characteristics

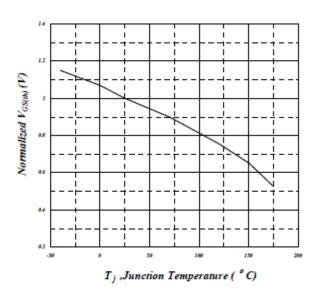


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

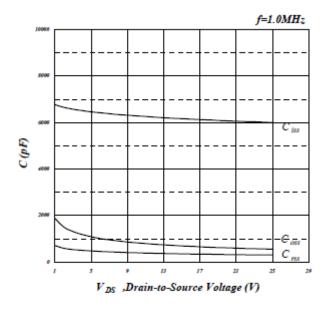


Fig 8. Typical Capacitance Characteristics

# TYPICAL CHARACTERISTICS

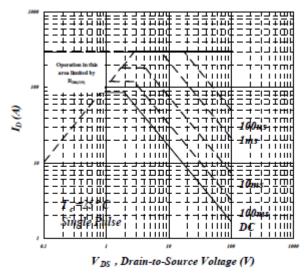


Fig 9. Maximum Safe Operating Area

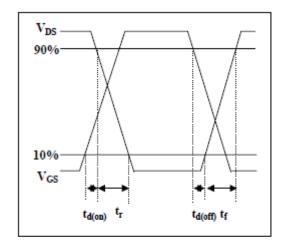


Fig 11. Switching Time Waveform

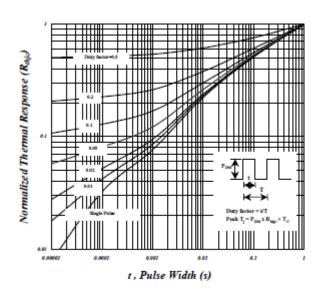


Fig 10. Effective Transient Thermal Impedance

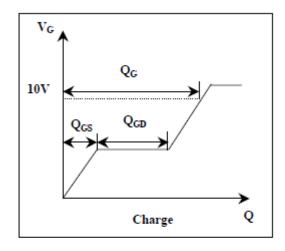
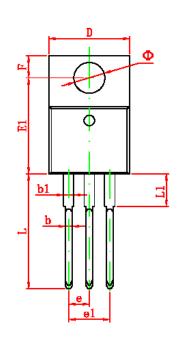
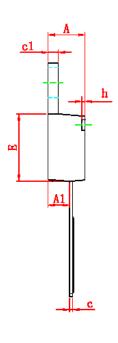


Fig 12. Gate Charge Waveform



# **TO-220 PACKAGE OUTLINE**





Symbol	Dimensions In Millimeters		Dimensions In Inches		
Syllibol	Min	Max	Min	Max	
Α	4.470	4.670	0.176	0.184	
A1	2.520	2.820	0.099	0.111	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
E	8.500	8.900	0.335	0.350	
E1	12.060	12.460	0.475	0.491	
е	2.540 TYP		0.100 TYP		
e1	4.980	5.180	0.196	0.204	
F	2.590	2.890	0.102	0.114	
h	0.000	0.300	0.000	0.012	
L	13.400	13.800	0.528	0.543	
L1	3.560	3.960	0.140	0.156	
• •	3.735	3.935	0.147	0.155	

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